

# DMP2160UW-7-VB Datasheet

# P-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>c</sup>	Q <sub>g</sub> (Typ.)			
- 20	0.080 at V <sub>GS</sub> = - 4.5 V	- 3.1	4.3 nC			
	0.100 at V <sub>GS</sub> = - 2.5 V	- 2.3	4.5110			

# **FEATURES**

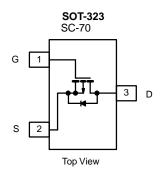
- Halogen-free According to IEC 61249-2-21 **Definition**
- Trench Power MOSFET 100 %  $R_g$  Tested
- Compliant to RoHS Directive 2002/95/EC

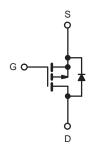


HALOGEN FREE

# **APPLICATIONS**

- Load Switch
- DC/DC Converters





P-Channel MOSFET

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	- 20	V	
Gate-Source Voltage		V <sub>GS</sub>	± 12	V
	T <sub>C</sub> = 25 °C		- 3.1	
Continuous Drain Current (T. – 150 °C)	T <sub>C</sub> = 70 °C	1 ,	- 2.1	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	- 1.4 <sup>a, b</sup>	
	T <sub>A</sub> = 70 °C		- 1.1 <sup>a, b</sup>	Α
Pulsed Drain Current	I <sub>DM</sub>	- 6		
Ocationary Course Basis Binds Course t	T <sub>C</sub> = 25 °C	I-	- 0.4	
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	- 0.3	
	T <sub>C</sub> = 25 °C		0.5	
Manianan Banas Biasinatian	T <sub>C</sub> = 70 °C	P <sub>D</sub>	0.3	w
Maximum Power Dissipation	T <sub>A</sub> = 25 °C		0.4 <sup>a, b</sup>	VV
	T <sub>A</sub> = 70 °C		0.3 <sup>a, b</sup>	
Operating Junction and Storage Temperature Rang	T <sub>J</sub> , T <sub>stg</sub>	- 50 to 150	°C	
Soldering Recommendations (Peak Temperature)		260		

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Based on  $T_C$  = 25 °C.



THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient <sup>a, b</sup>	t ≤ 10 s	R <sub>thJA</sub>	250	300	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	$R_{thJF}$	225	270	C/VV		

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. Maximum under steady state conditions is 360 °C/W.

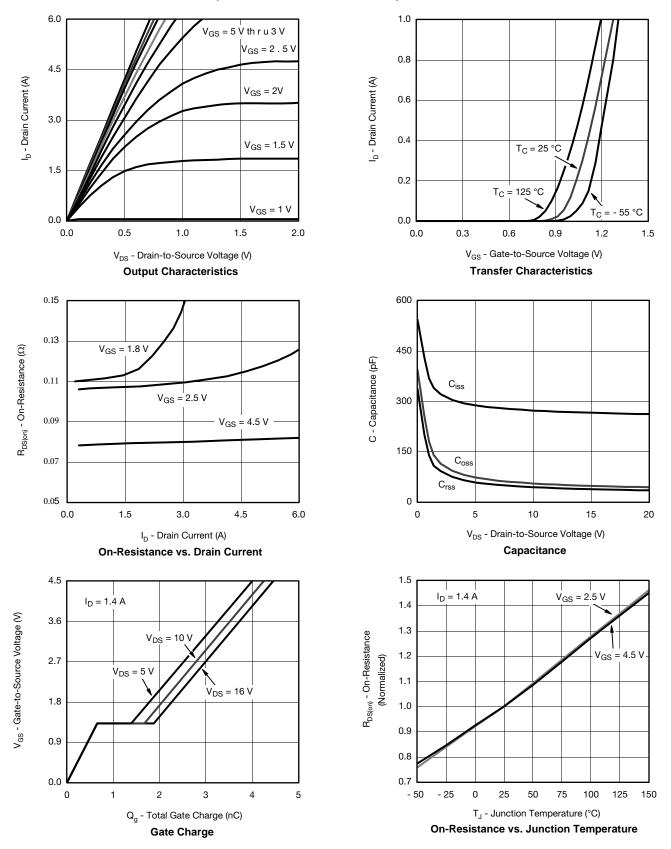
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = - 250 μA				V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	1 - 250		- 14		mV/°C
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = - 250 μA		2.4		
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = - 250 μA	- 0.45		- 1.5	V
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA
Zara Cata Valtaga Praia Current	I <sub>DSS</sub>	V <sub>DS</sub> = - 20 V, V <sub>GS</sub> = 0 V			- 1	
Zero Gate Voltage Drain Current		V <sub>DS</sub> = - 20 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			- 10	μA
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 2			Α
	, ,	V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 1.4 A		0.080		Ω
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 2.5 V, I <sub>D</sub> = - 1.2 A		0.100		
	,	V <sub>GS</sub> = - 1.8 V, I <sub>D</sub> = - 0.3 A		0.140		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 5 V, I <sub>D</sub> = - 1.4 A		5		S
Dynamic <sup>b</sup>						
Input Capacitance	C <sub>iss</sub>			272		pF
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = - 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz		55		
Reverse Transfer Capacitance	C <sub>rss</sub>			44		
T	Q <sub>g</sub>	$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -1.4 \text{ A}$	4 A 4.3		6.5	
Total Gate Charge		50 5		2.7	4.1	nC
Gate-Source Charge		$V_{DS} = -10 \text{ V}, V_{GS} = -2.5 \text{ V}, I_{D} = -1.4 \text{ A}$		0.7		
Gate-Drain Charge	$Q_{gd}$			1.0		
Gate Resistance	R <sub>q</sub>	f = 1 MHz	1.4	7	14	Ω
Turn-On Delay Time	t <sub>d(on)</sub>			12	20	
Rise Time	t <sub>r</sub>	$V_{DD} = -10 \text{ V}, R_1 = 9.1 \Omega$		20	30	ns
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D \cong -1.1 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$		23	35	
Fall Time	t <sub>f</sub>	_		9	18	
Turn-On Delay Time	t <sub>d(on)</sub>			5	10	
Rise Time	t <sub>r</sub>	$V_{DD} = -10 \text{ V}, R_1 = 9.1 \Omega$		10	20	
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D \cong -1.1 \text{ A}, V_{GEN} = -8 \text{ V}, R_g = 1 \Omega$		18	27	
Fall Time	t <sub>f</sub>	Ĭ		7	14	
Drain-Source Body Diode Characterist						
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			- 2.4	
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>	Ü			- 6	A
Body Diode Voltage	V <sub>SD</sub>	I <sub>F</sub> = - 0.7 A		- 0.8	- 1.2	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>	·		18	27	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			7	14	nC
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = -0.7 \text{ A}, \text{ dI/dt} = 100 \text{ A/µs}, T_J = 25 ^{\circ}\text{C}$		7		1
Reverse Recovery Rise Time	t <sub>b</sub>			11		ns

### Notes:

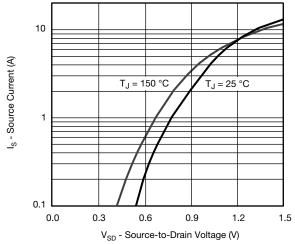
- a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

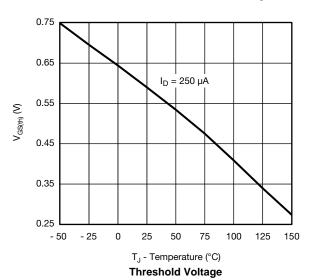


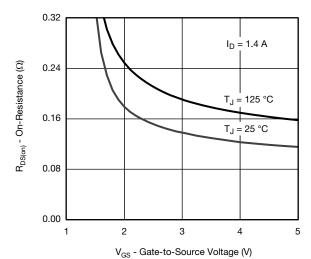




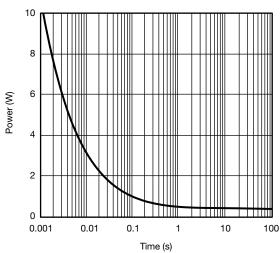


#### Source-Drain Diode Forward Voltage

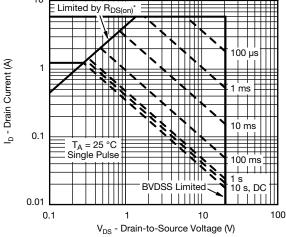




On-Resistance vs. Gate-to-Source Voltage



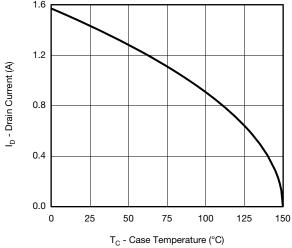
Single Pulse Power, Junction-to-Ambient



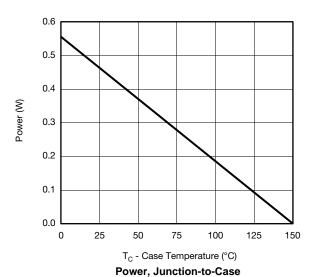
\*  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

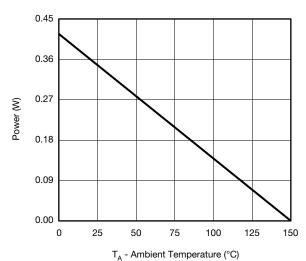
Safe Operating Area, Junction-to-Ambient







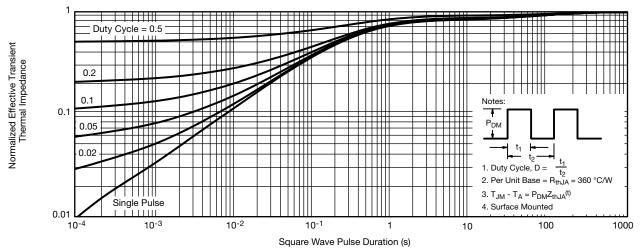




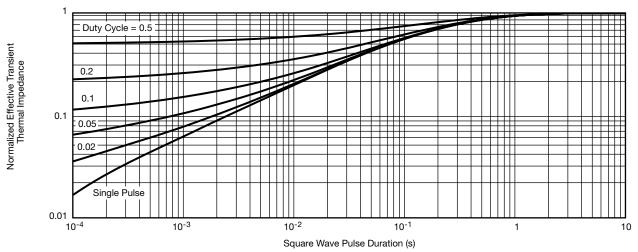
Power, Junction-to-Ambient

<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





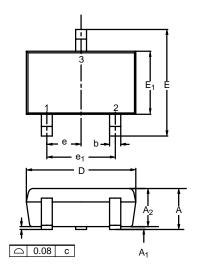
Normalized Thermal Transient Impedance, Junction-to-Ambient

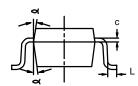


Normalized Thermal Transient Impedance, Junction-to-Foot



# SC-70: 3-LEADS



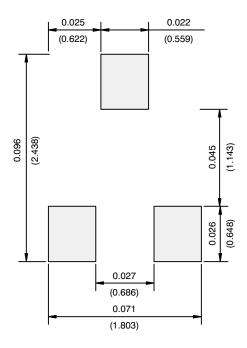


	MILLIMETERS			INCHES		
Dim	Min	Nom	Max	Min	Nom	Max
Α	0.90	_	1.10	0.035	-	0.043
<b>A</b> <sub>1</sub>	_	_	0.10	_	_	0.004
A <sub>2</sub>	0.80	_	1.00	0.031	_	0.039
b	0.25	_	0.40	0.010	_	0.016
С	0.10	_	0.25	0.004	-	0.010
D	1.80	2.00	2.20	0.071	0.079	0.087
Е	1.80	2.10	2.40	0.071	0.083	0.094
E <sub>1</sub>	1.15	1.25	1.35	0.045	0.049	0.053
е	0.65BSC			0.026BSC		
e <sub>1</sub>	1.20	1.30	1.40	0.047	0.051	0.055
L	0.10	0.20	0.30	0.004	0.008	0.012
۵		7°Nom		7°Nom		
ECN: S-03946—Rev. C, 09-Jul-01						

DWG: 5549



# **RECOMMENDED MINIMUM PADS FOR SC-70: 3-Lead**



Recommended Minimum Pads Dimensions in Inches/(mm)



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